US00D803283S

(12) **United States Design Patent** (10) **Patent No.: US D803,283 S**
Rashkovsky et al. (45) **Date of Patent:** ** **Nov. 21, 2017**

(54) **WAFER HANDLING ASSEMBLY**

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(**) Term: **15 Years**

(21) Appl. No.: **29/564,740**

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(51) **LOC (10) Cl.** **15-09**

(52) **U.S. Cl.**
USPC **D15/138**

(58) **Field of Classification Search**
USPC D3/315; D13/182; D15/138
(Continued)

(56) **References Cited**

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(74) *Attorney, Agent, or Firm* — Holzer Patel Drennan

(57) **CLAIM**

The ornamental design for a wafer handling assembly, as shown and described.

DESCRIPTION

FIG. **1** is a top perspective view of a first embodiment of a wafer handling assembly.

FIG. **2** is a top view of the wafer handling assembly of FIG. **1**.

FIG. **3** is a side view of the wafer handling assembly of FIG. **1**.

FIG. **4** is another side view of the wafer handling assembly of FIG. **1**.

FIG. **5** is a bottom perspective view of the wafer handling assembly of FIG. **1**.

FIG. **6** is a top perspective view of a second embodiment of a wafer handling assembly.

FIG. **7** is a top view of the wafer handling assembly of FIG. **6**.

FIG. **8** is a side view of the wafer handling assembly of FIG. **6**.

FIG. **9** is another side view of the wafer handling assembly of FIG. **6**.

FIG. **10** is a bottom perspective view of the wafer handling assembly of FIG. **6**.

FIG. **11** is a top perspective view of a third embodiment of a wafer handling assembly.

FIG. **12** is a top view of the wafer handling assembly of FIG. **11**.

FIG. **13** is a side view of the wafer handling assembly of FIG. **11**.

FIG. **14** is another side view of the wafer handling assembly of FIG. **11**.

FIG. **15** is a bottom perspective view of the wafer handling assembly of FIG. **11**.

FIG. **16** is a top perspective view of a fourth embodiment of a wafer handling assembly.

FIG. **17** is a top view of the wafer handling assembly of FIG. **16**.

FIG. **18** is a side view of the wafer handling assembly of FIG. **16**.

FIG. **19** is another side view of the wafer handling assembly of FIG. **16**.

FIG. **20** is a bottom perspective view of the wafer handling assembly of FIG. **16**.

FIG. **21** is a top perspective view of a fifth embodiment of a wafer handling assembly.

FIG. **22** is a top view of the wafer handling assembly of FIG. **21**.

FIG. **23** is a side view of the wafer handling assembly of FIG. **21**.

FIG. **24** is another side view of the wafer handling assembly of FIG. **21**.

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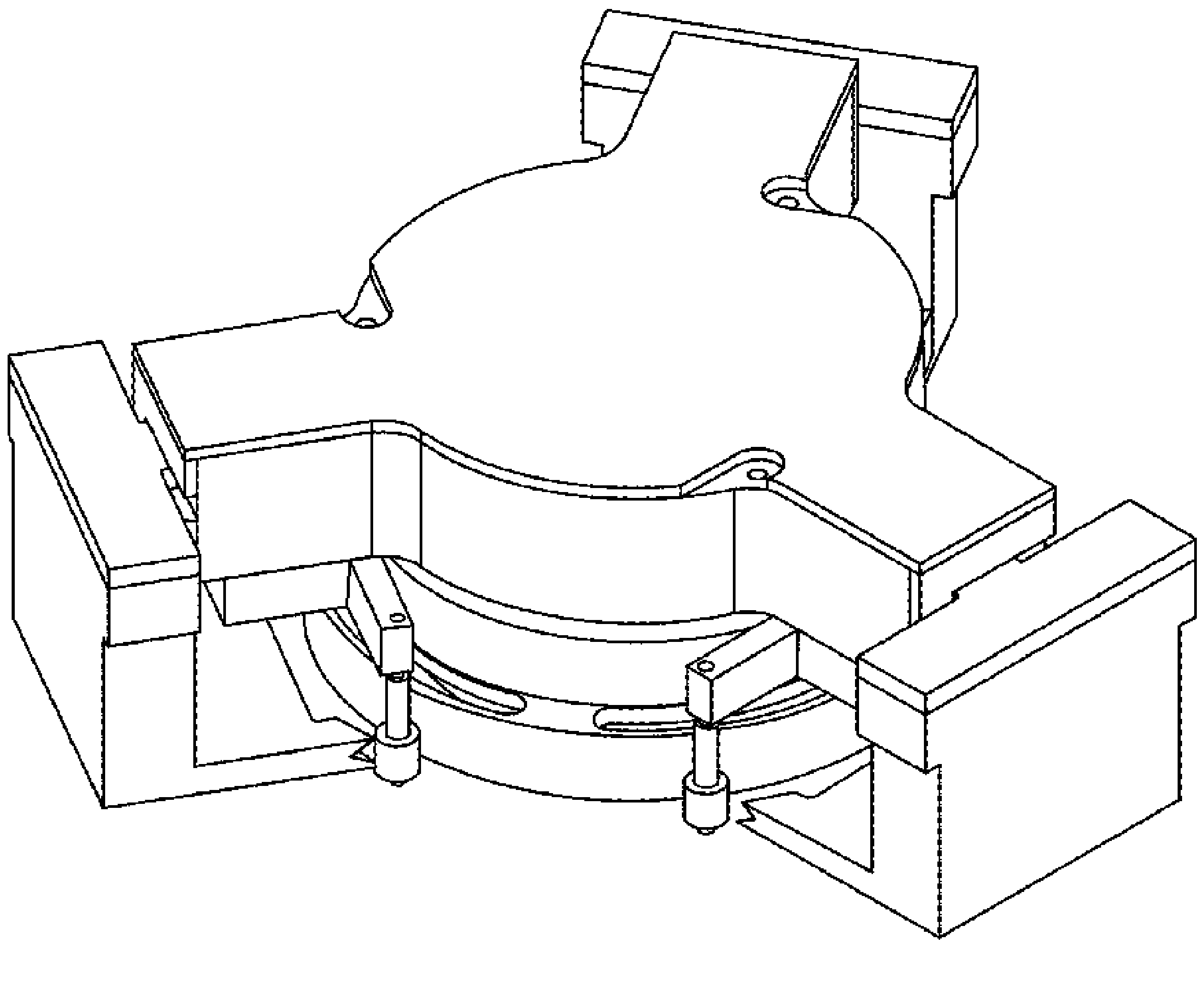

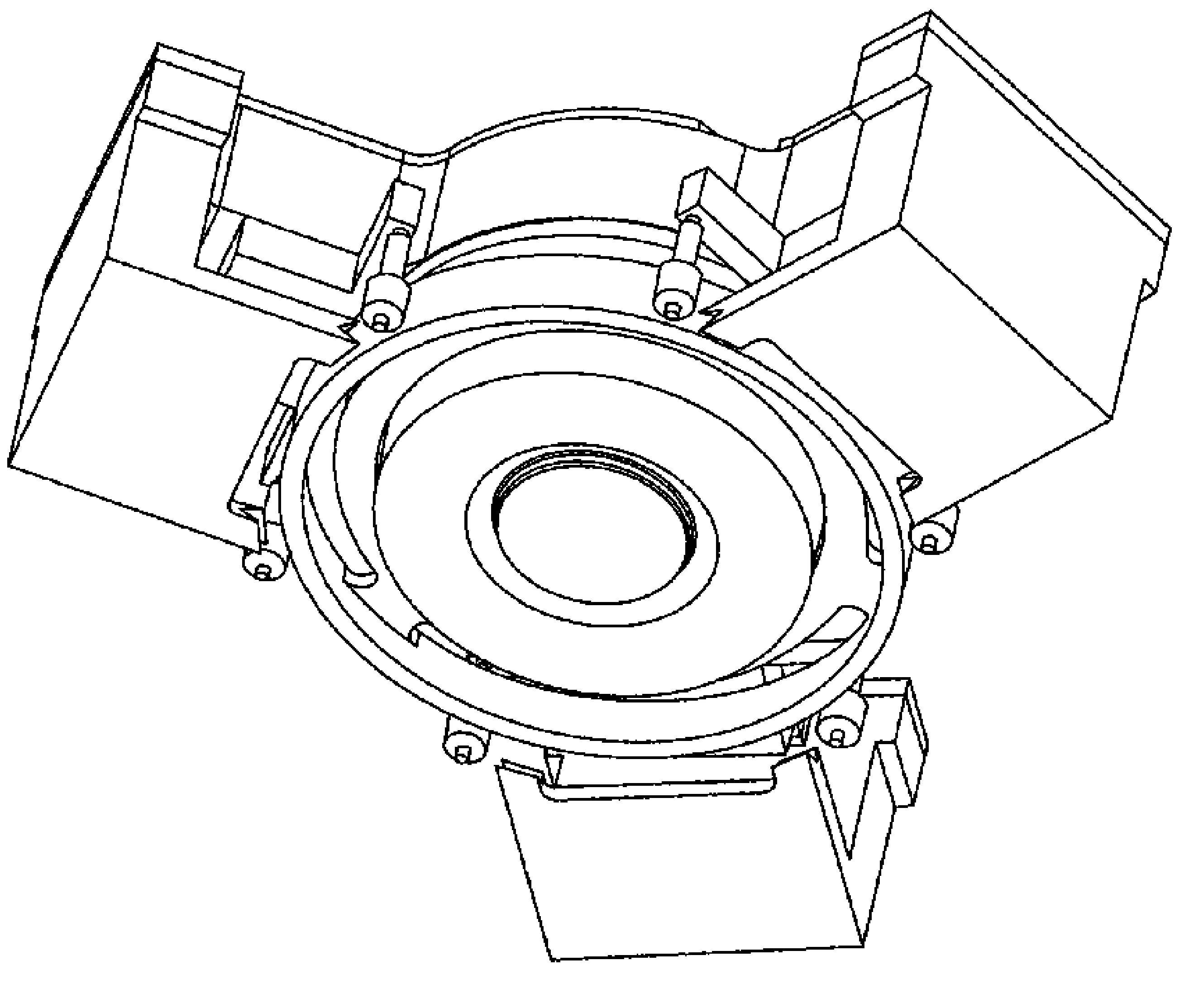

FIG. **25** is a bottom perspective view of the wafer handling assembly of FIG. **21**.

FIG. **26** is a top perspective view of a sixth embodiment of a wafer handling assembly.

FIG. **27** is a top view of the wafer handling assembly of FIG. **26**.

FIG. **28** is a side view of the wafer handling assembly of FIG. **26**.

FIG. **29** is another side view of the wafer handling assembly of FIG. **26**; and,

FIG. **30** is a bottom perspective view of the wafer handling assembly of FIG. **26**.

1 Claim, 30 Drawing Sheets

(58) **Field of Classification Search**
CPC B25J 15/0028; B25J 15/0052; B25J 11/0095; H01L 21/6838; H01L 21/68742
See application file for complete search history.

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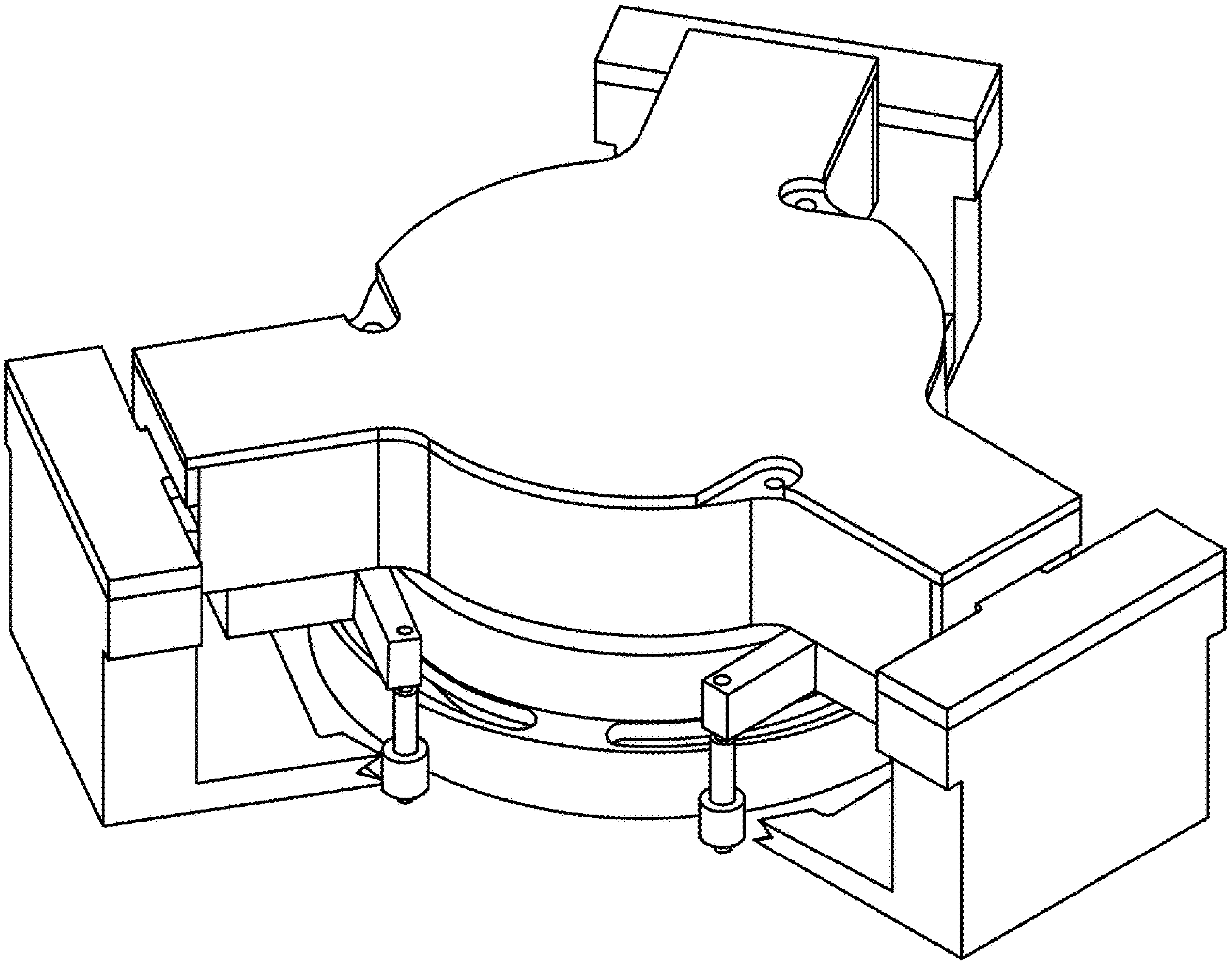


FIG. 1

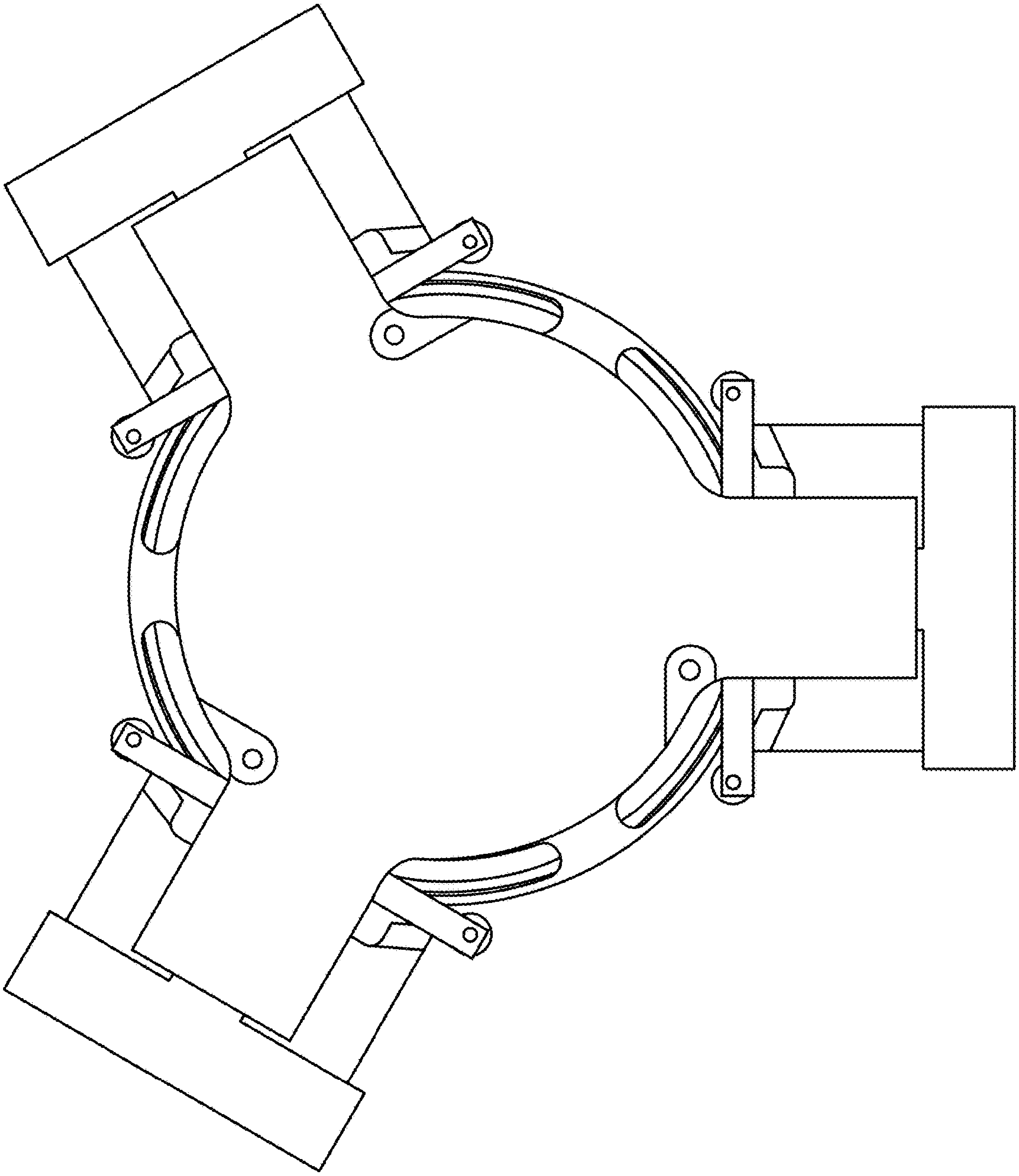


FIG. 2

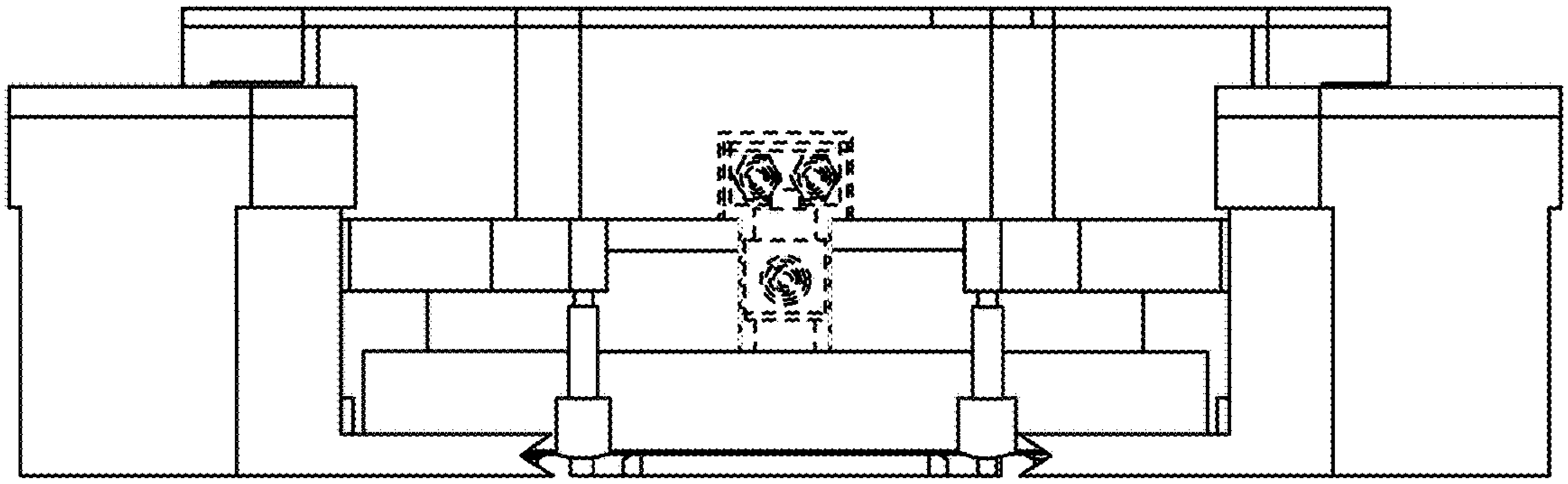
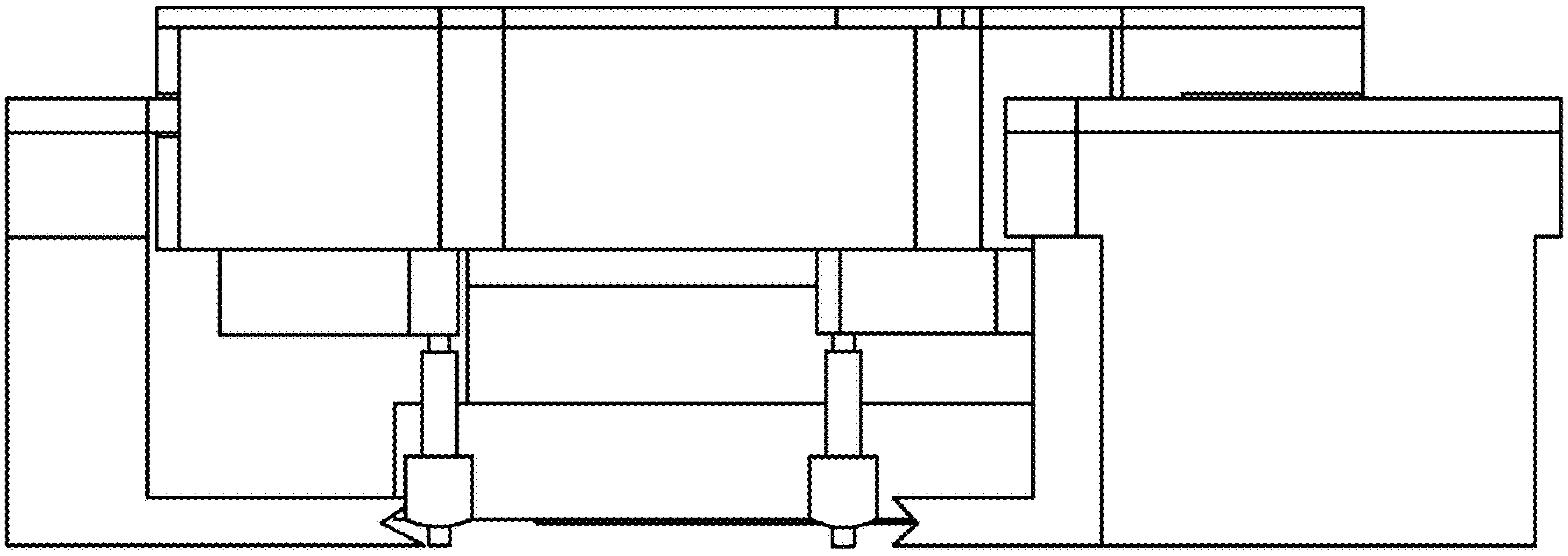


FIG. 3



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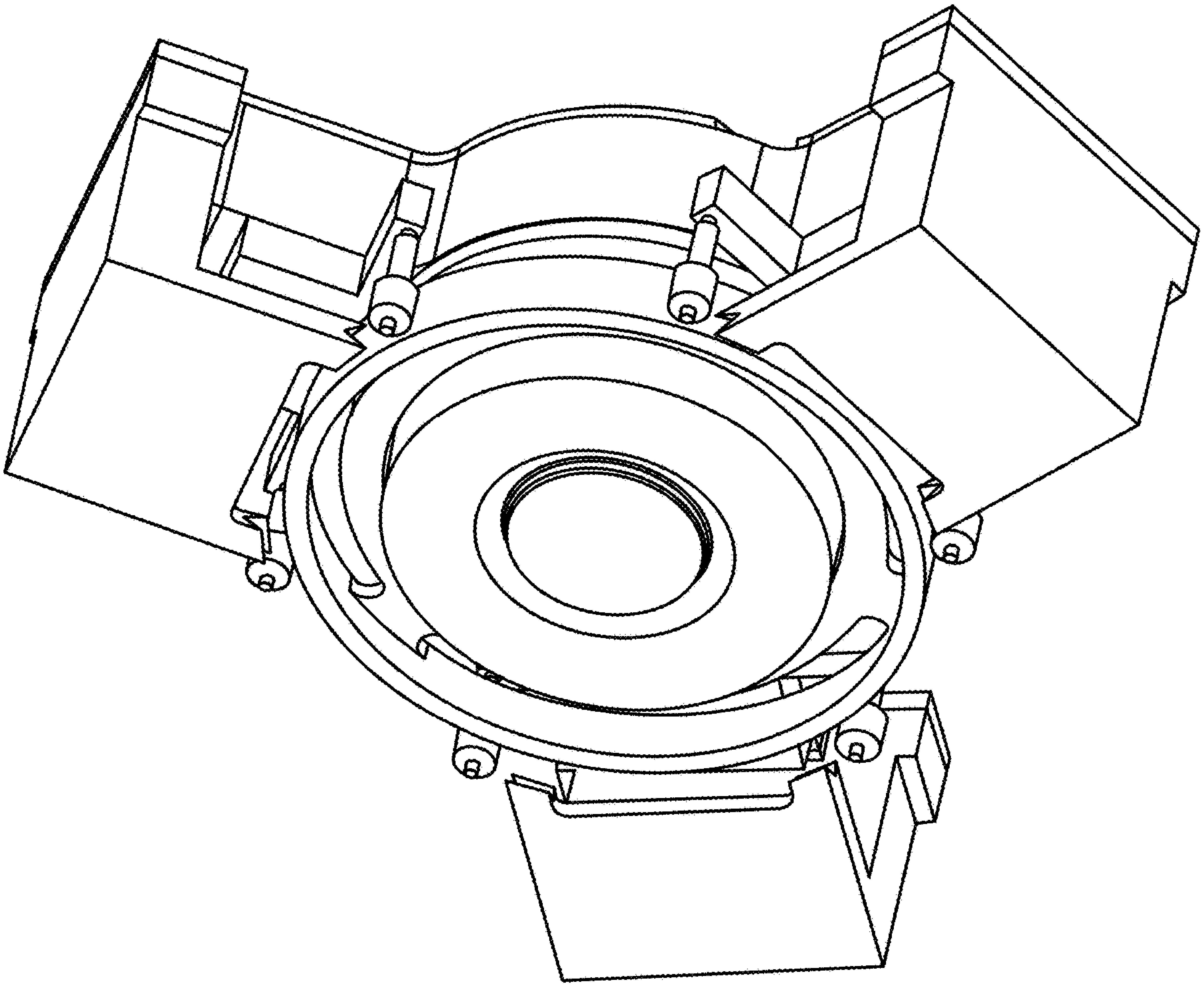
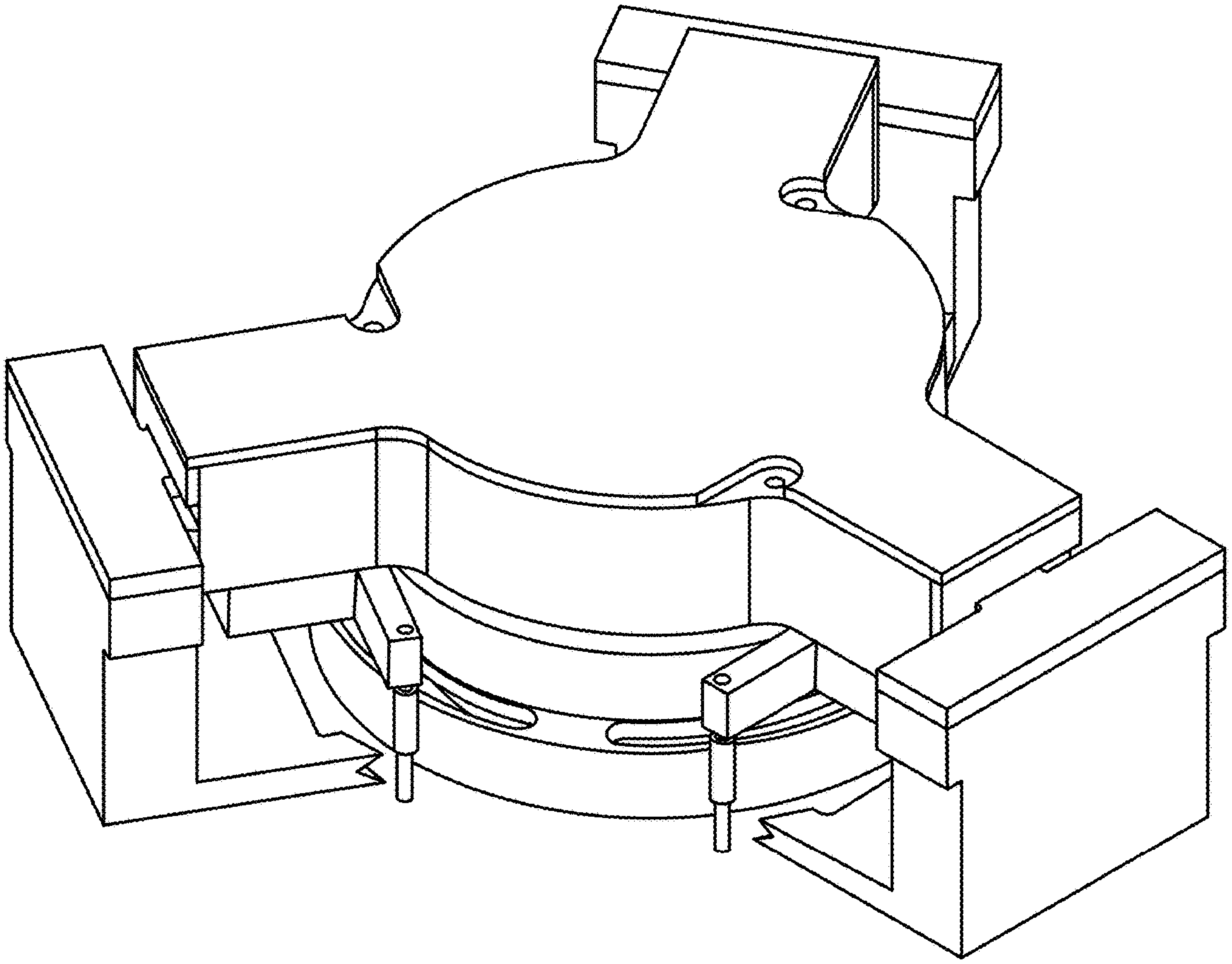


FIG. 5



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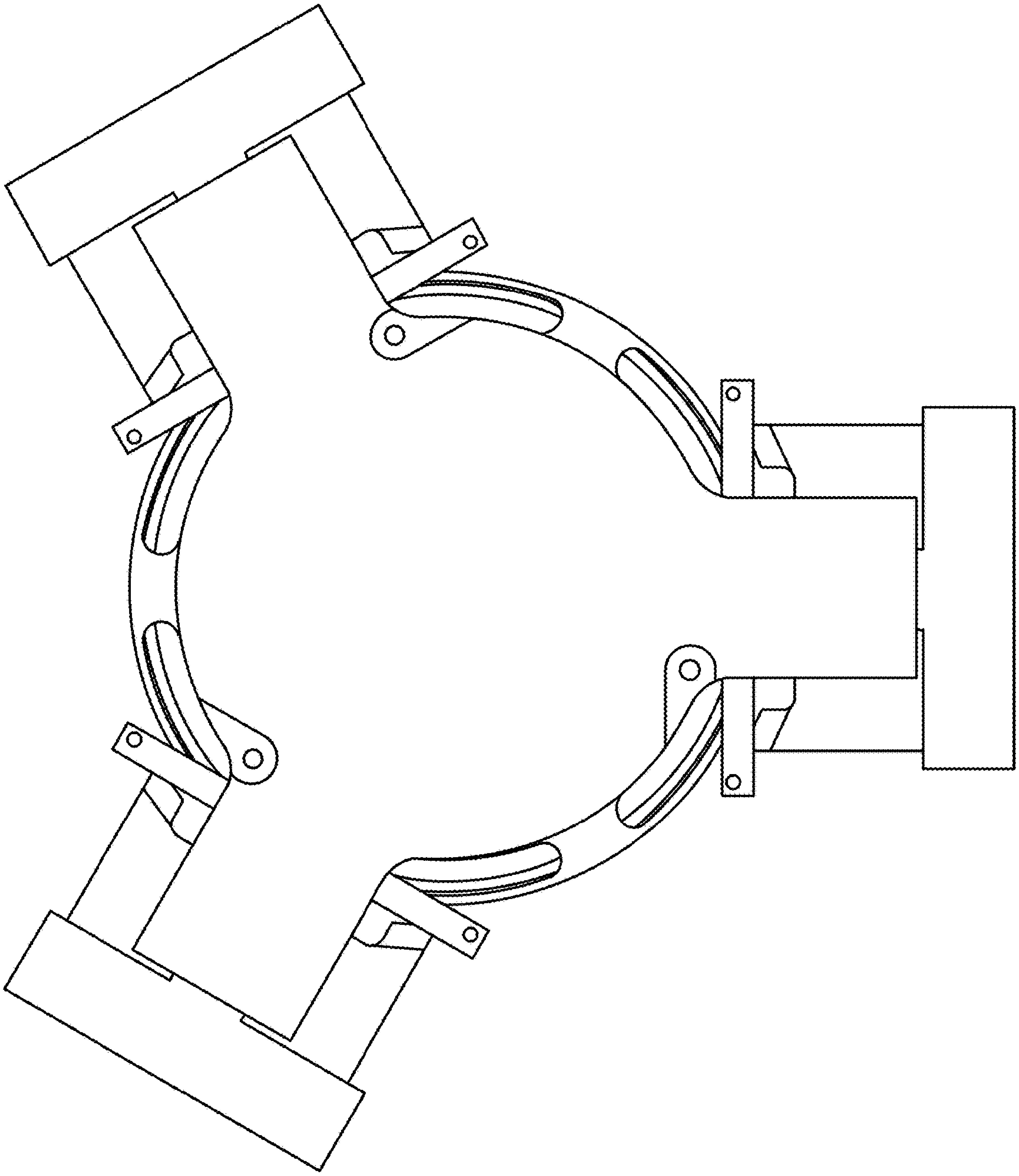

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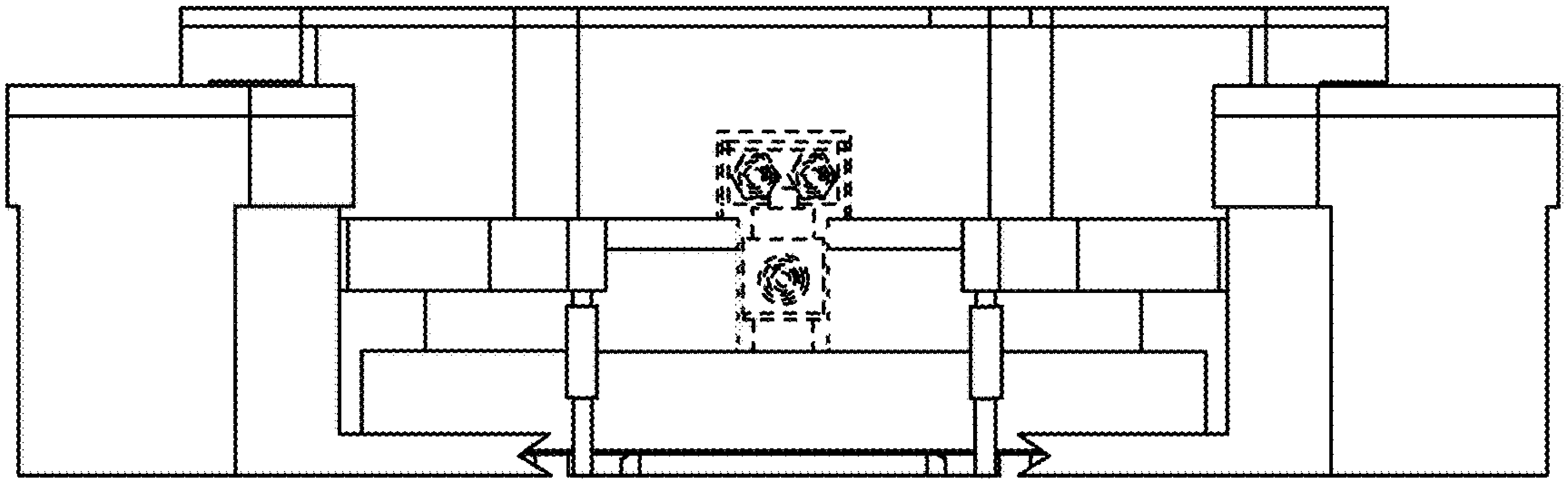

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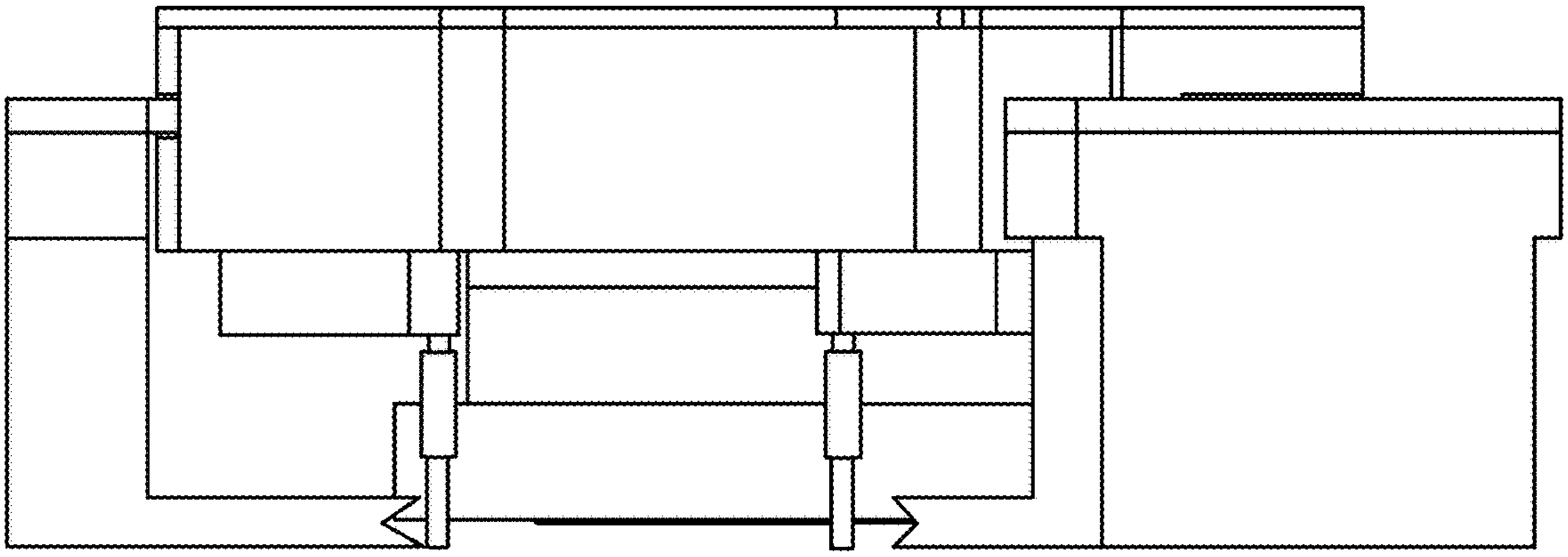

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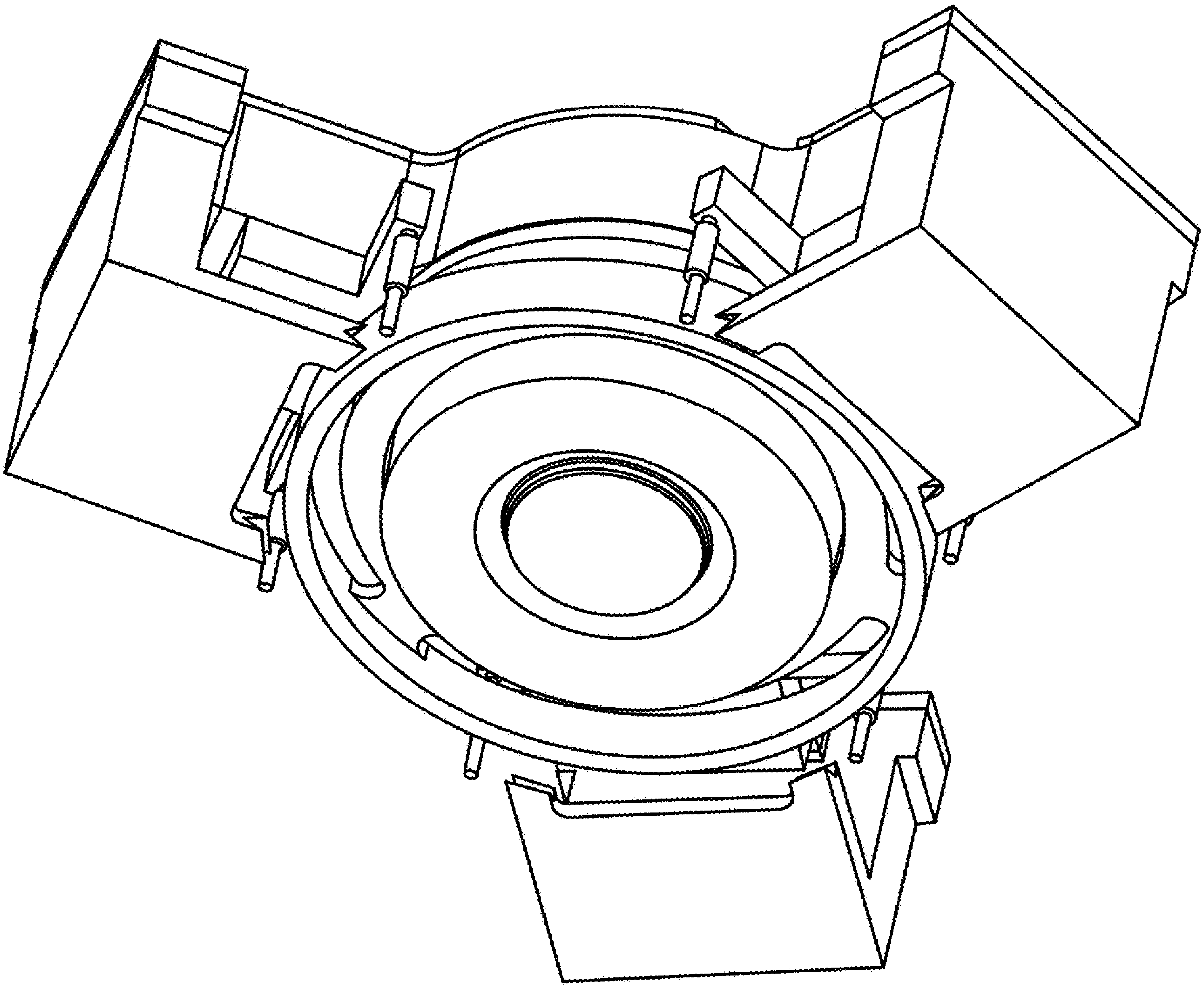

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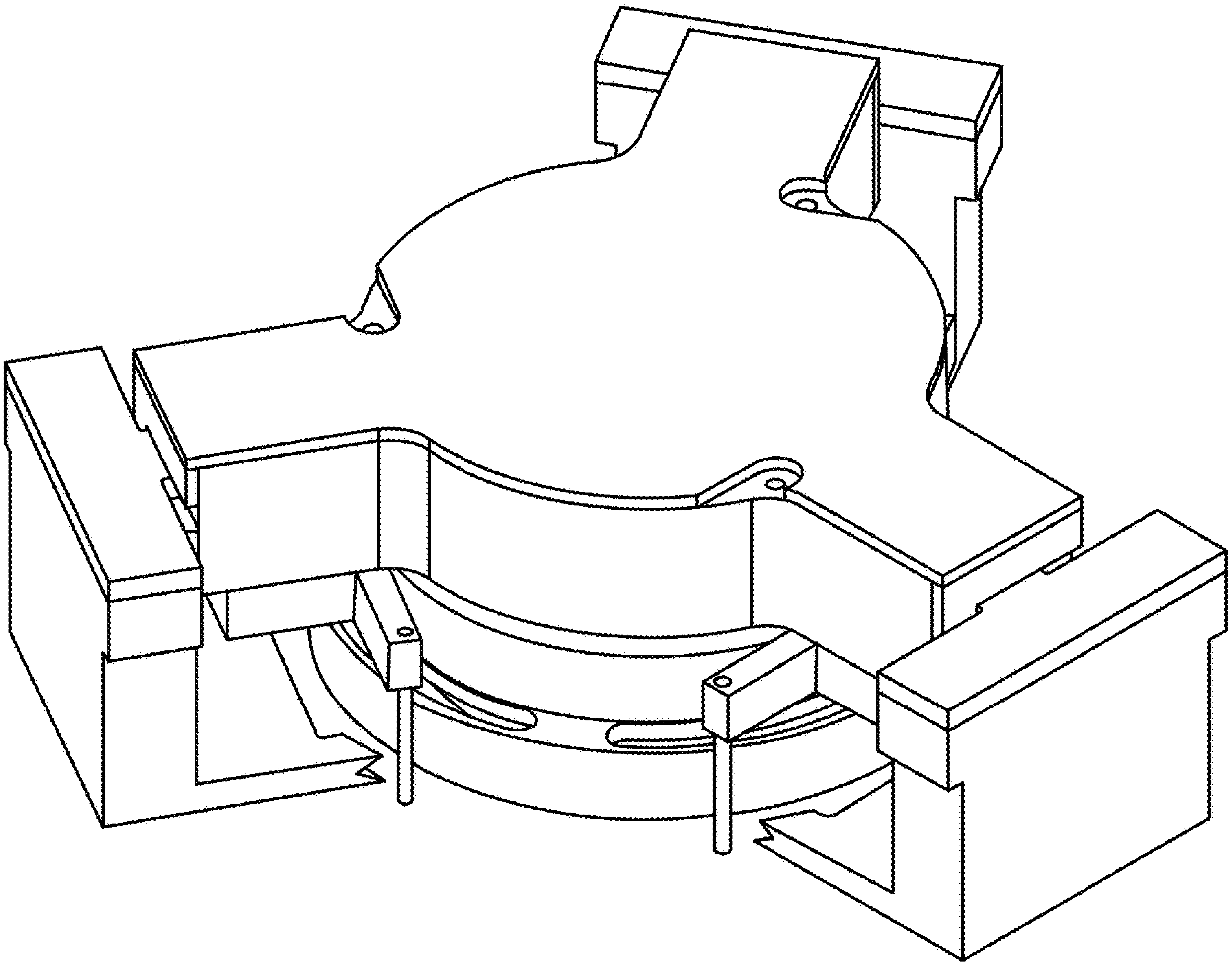

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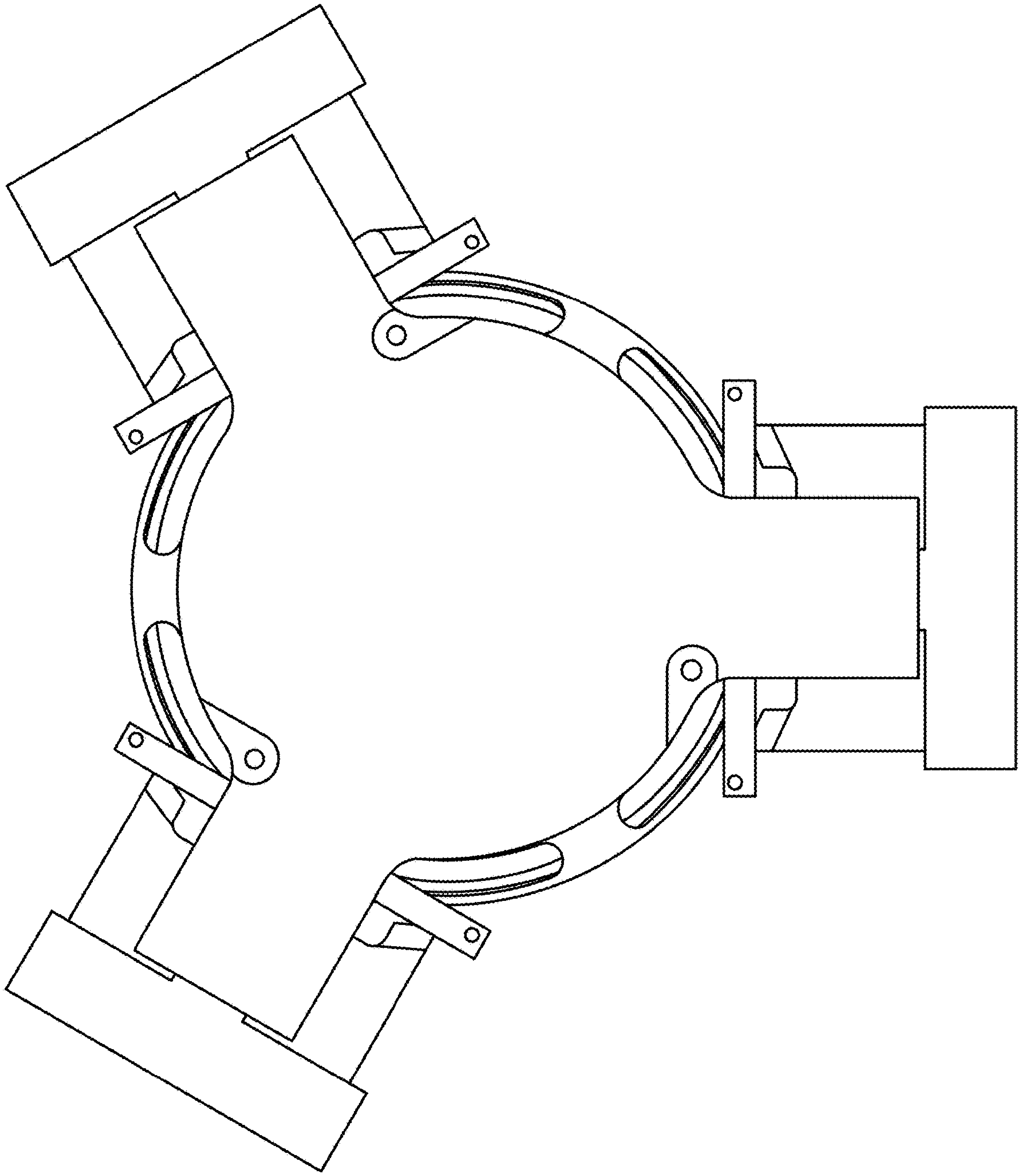

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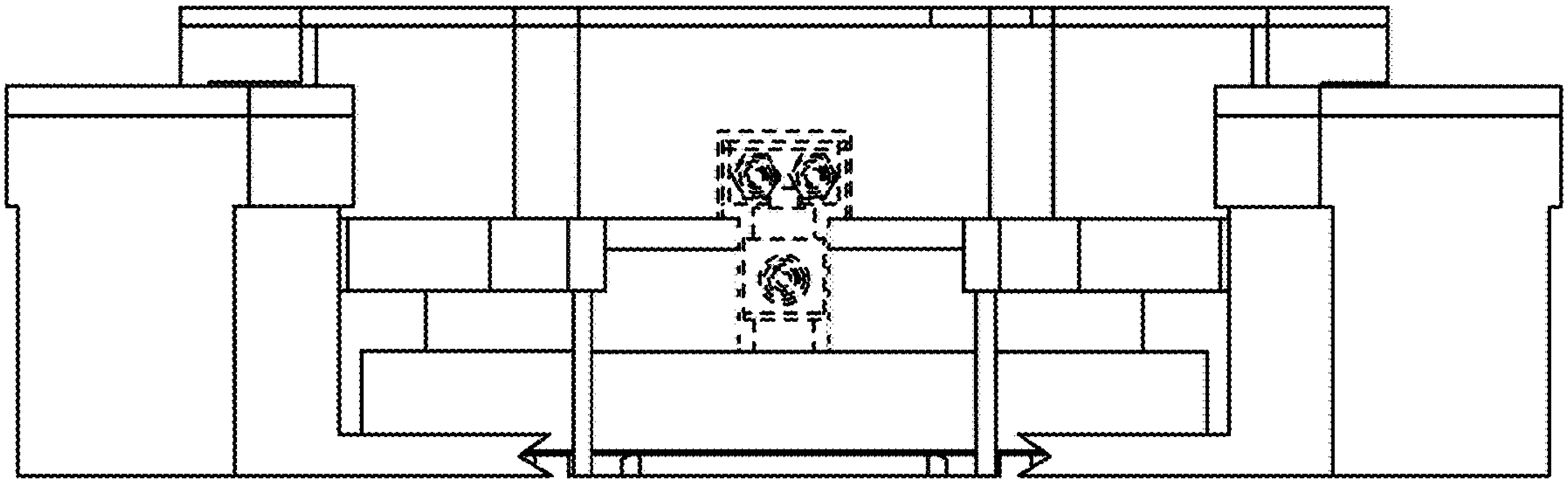

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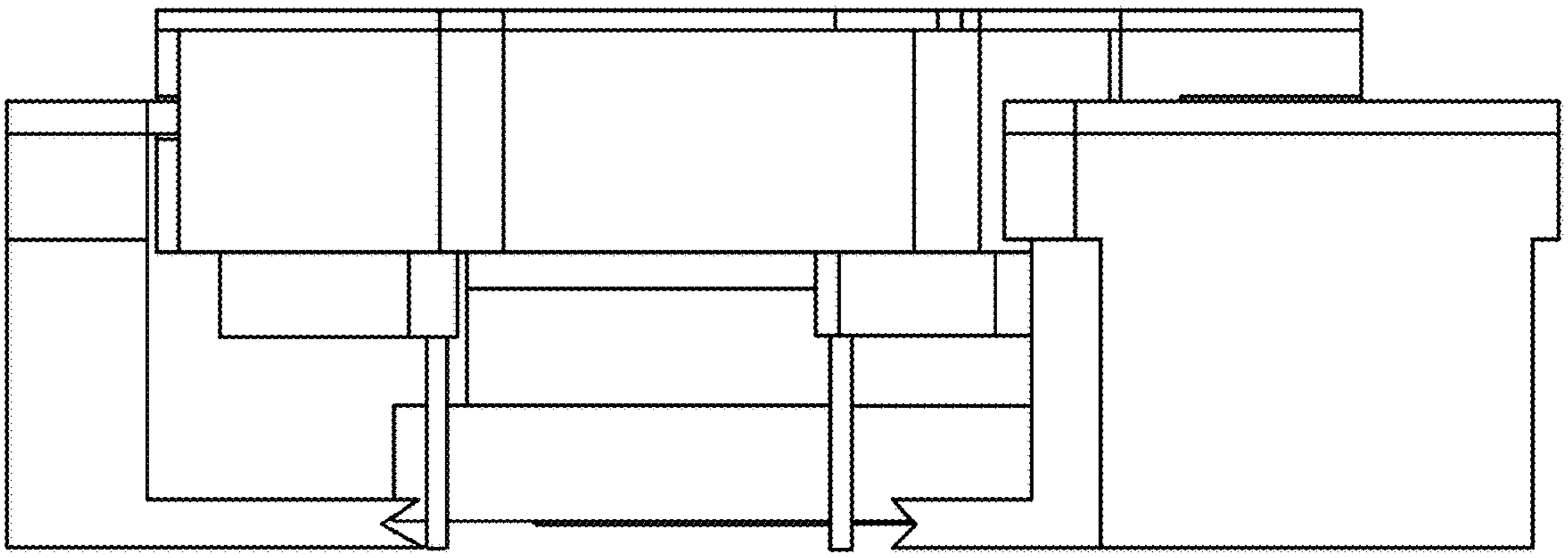

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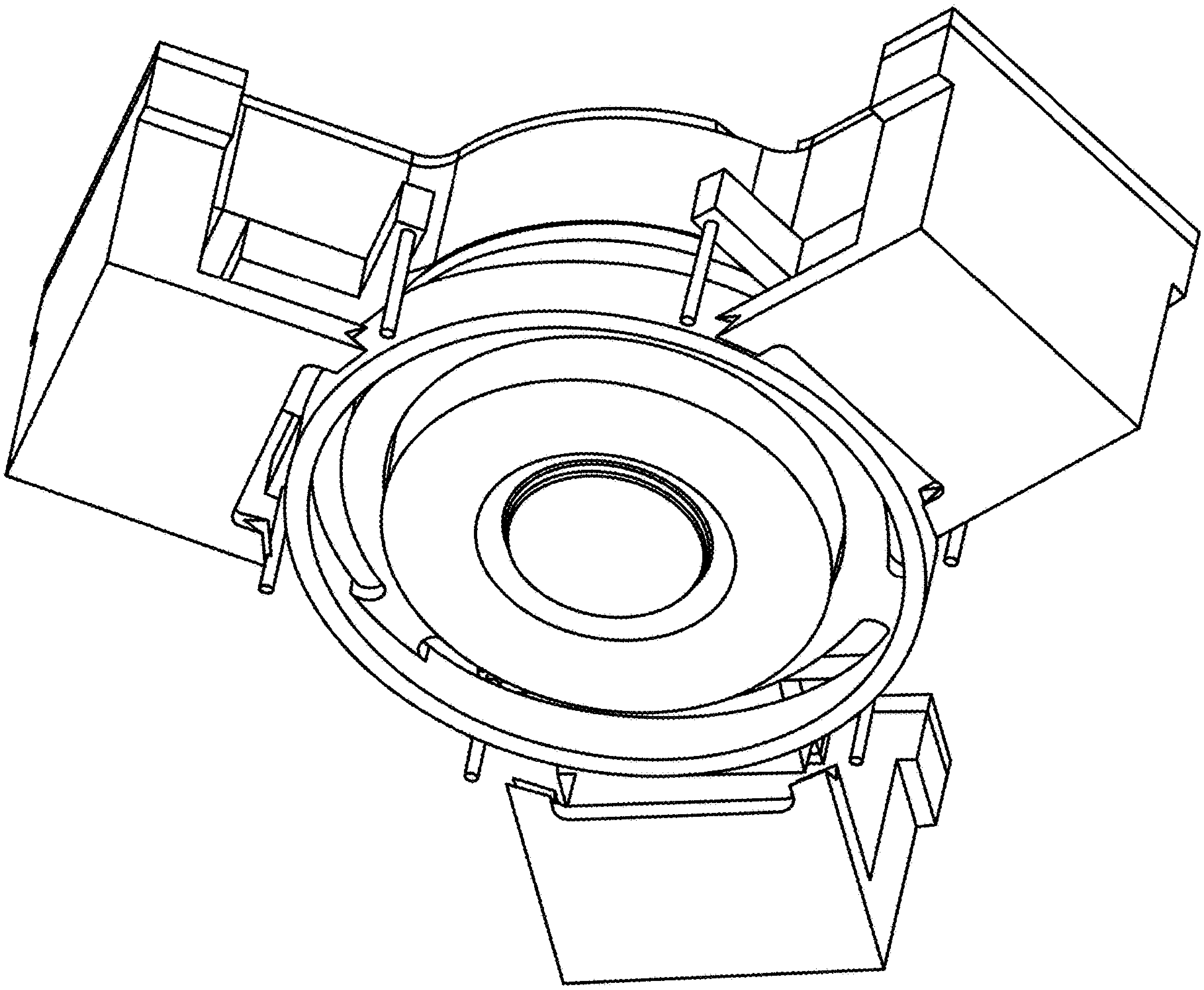

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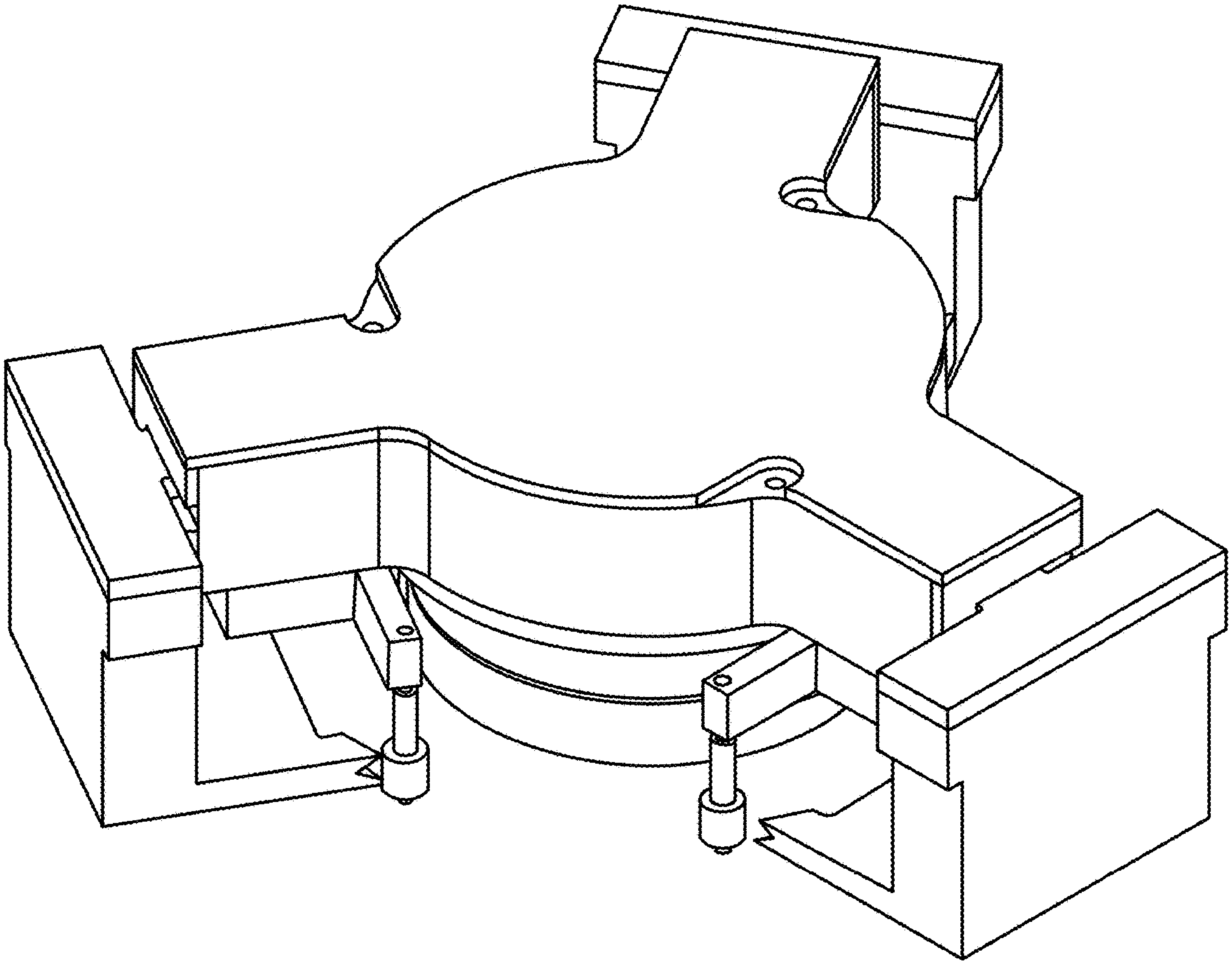

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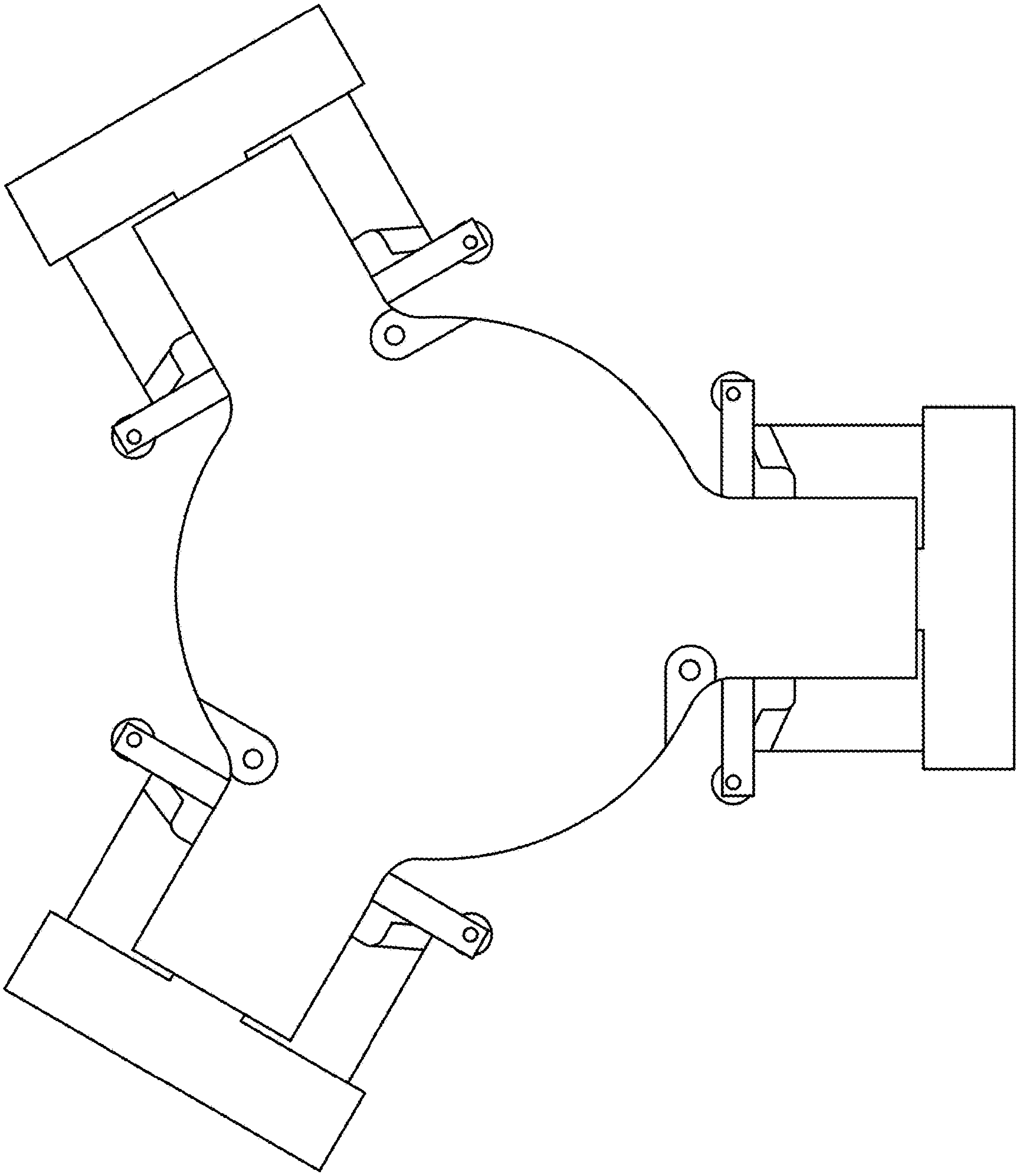

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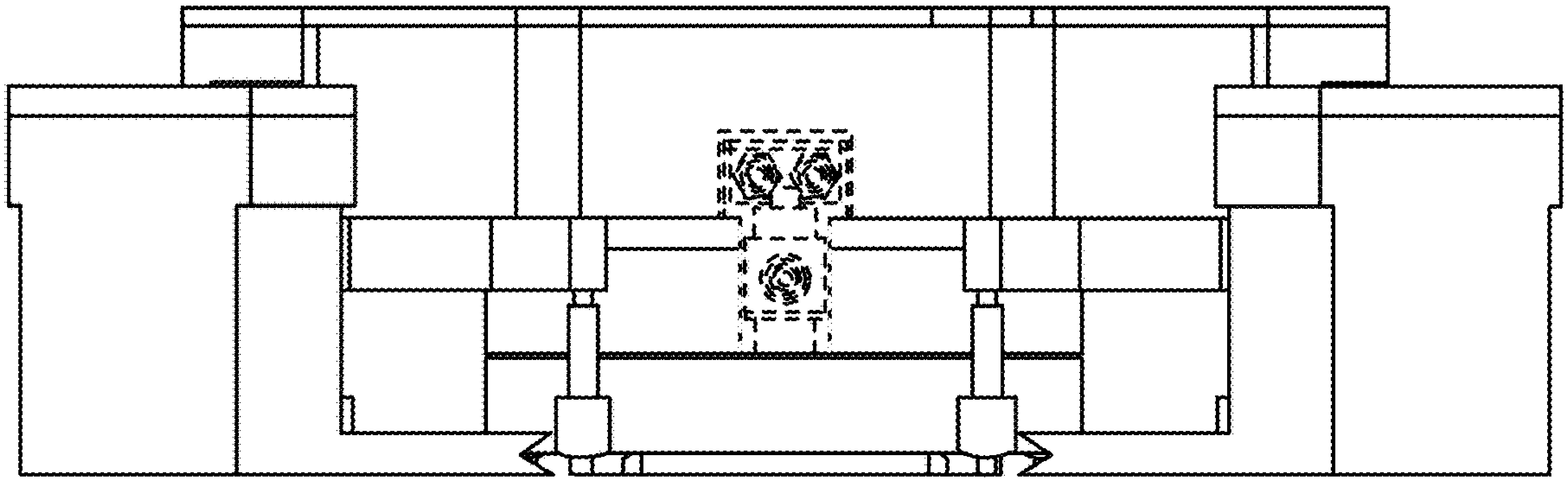

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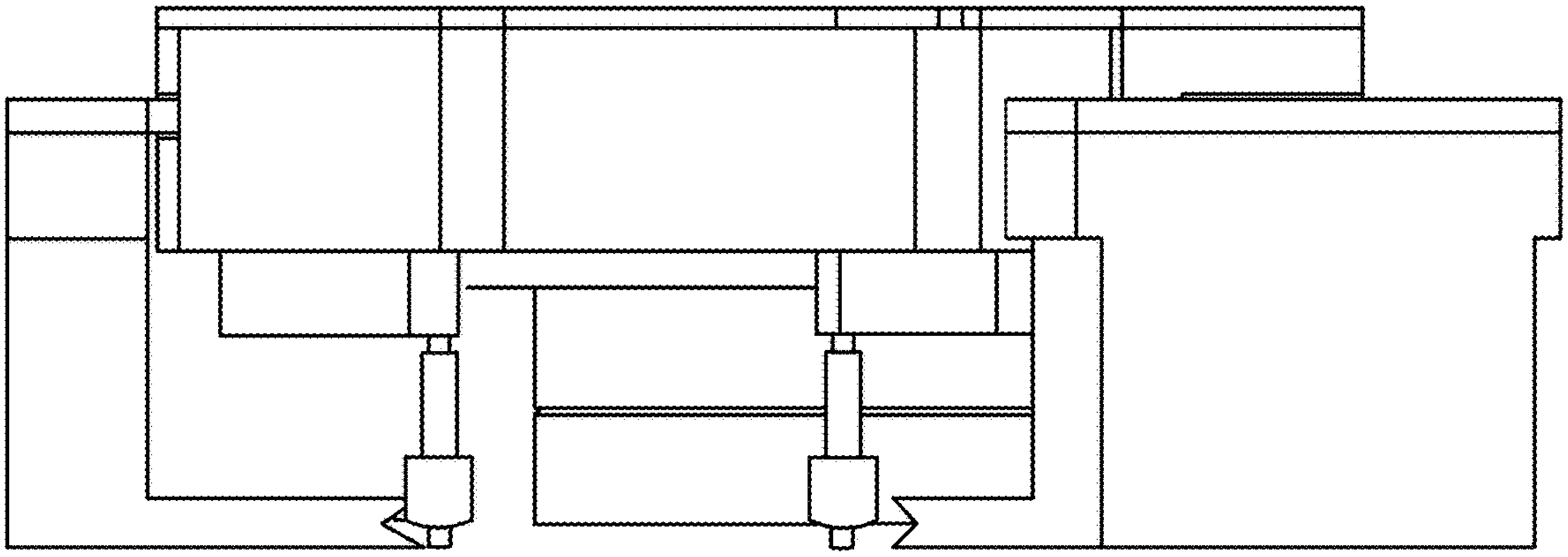

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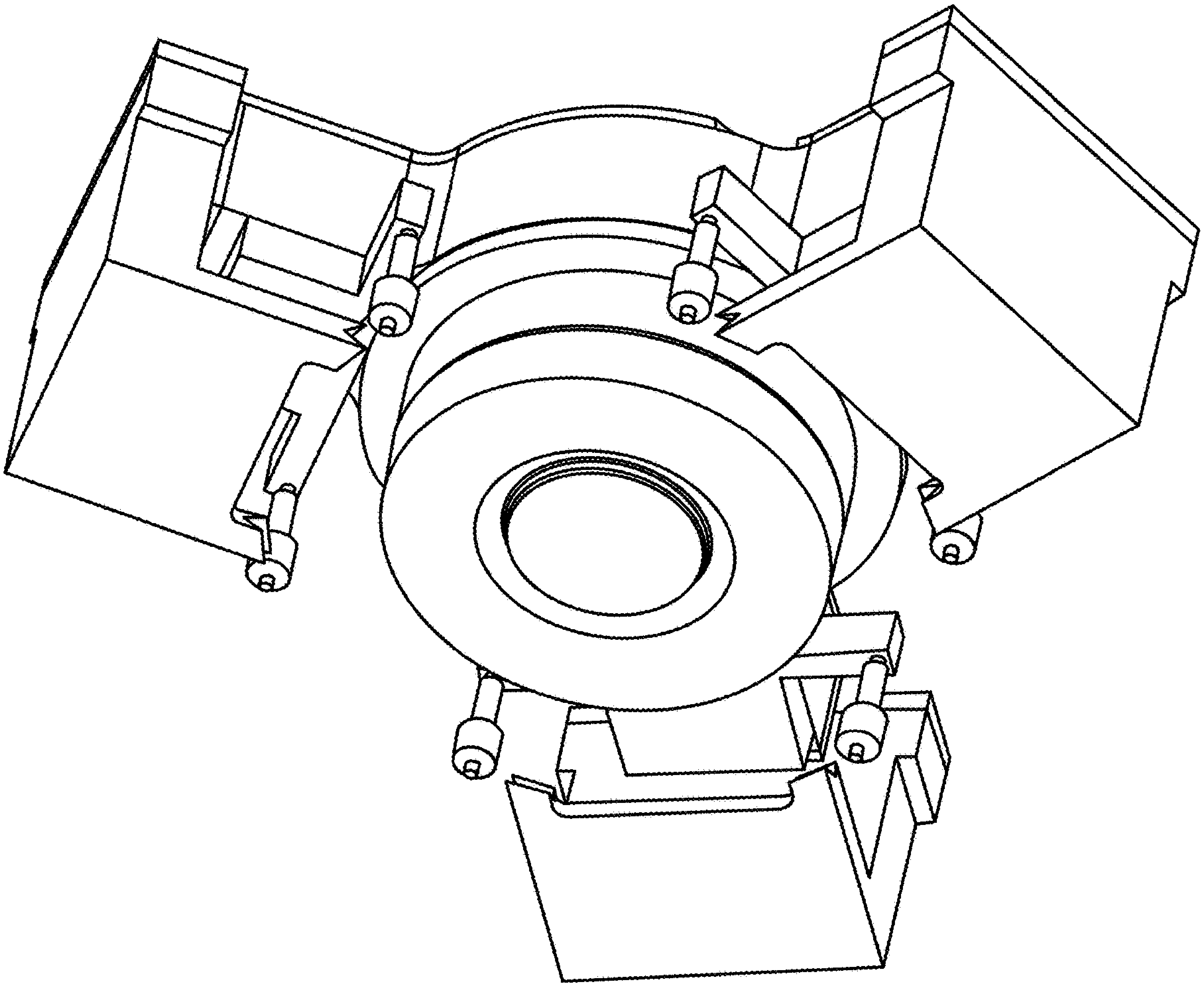

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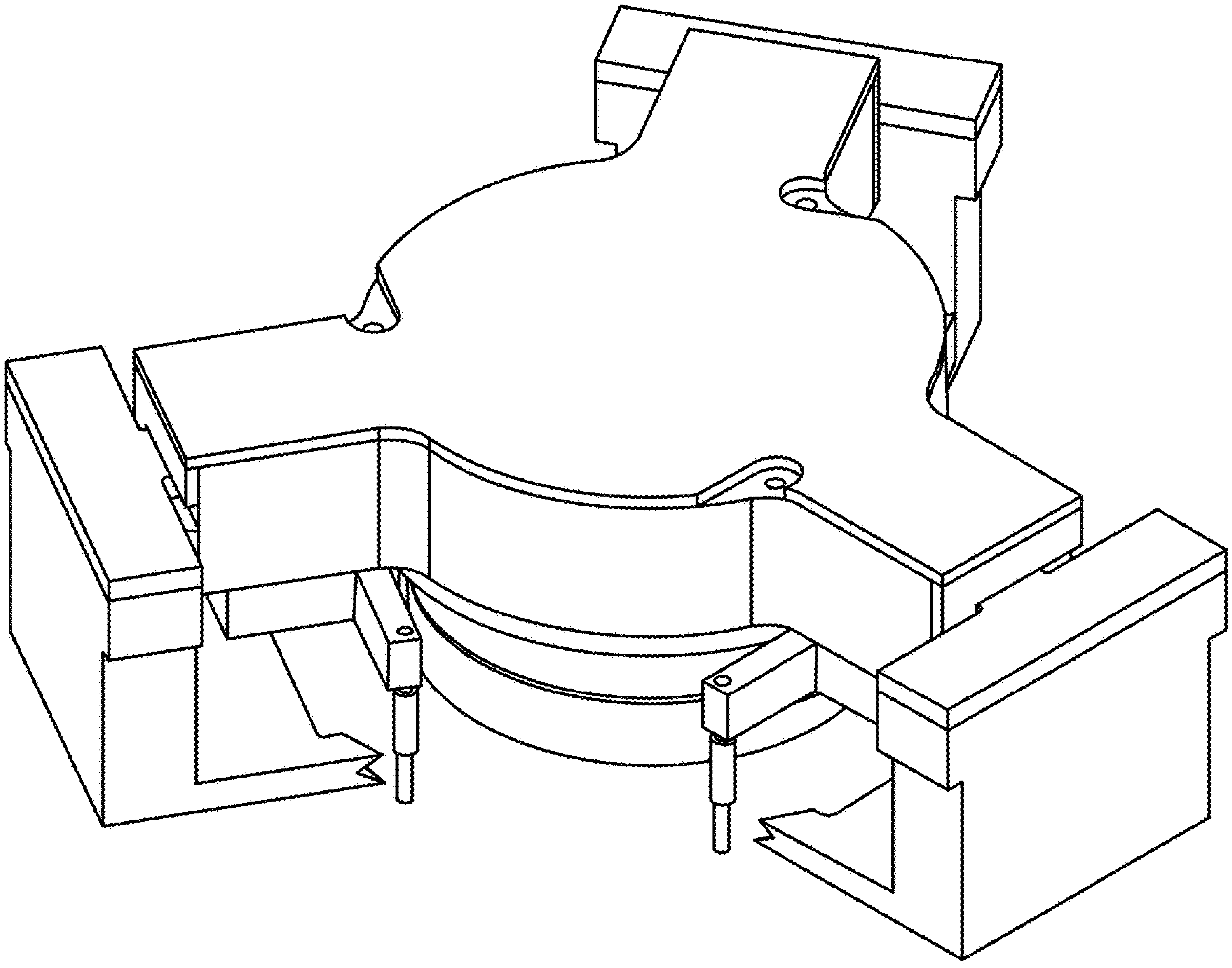

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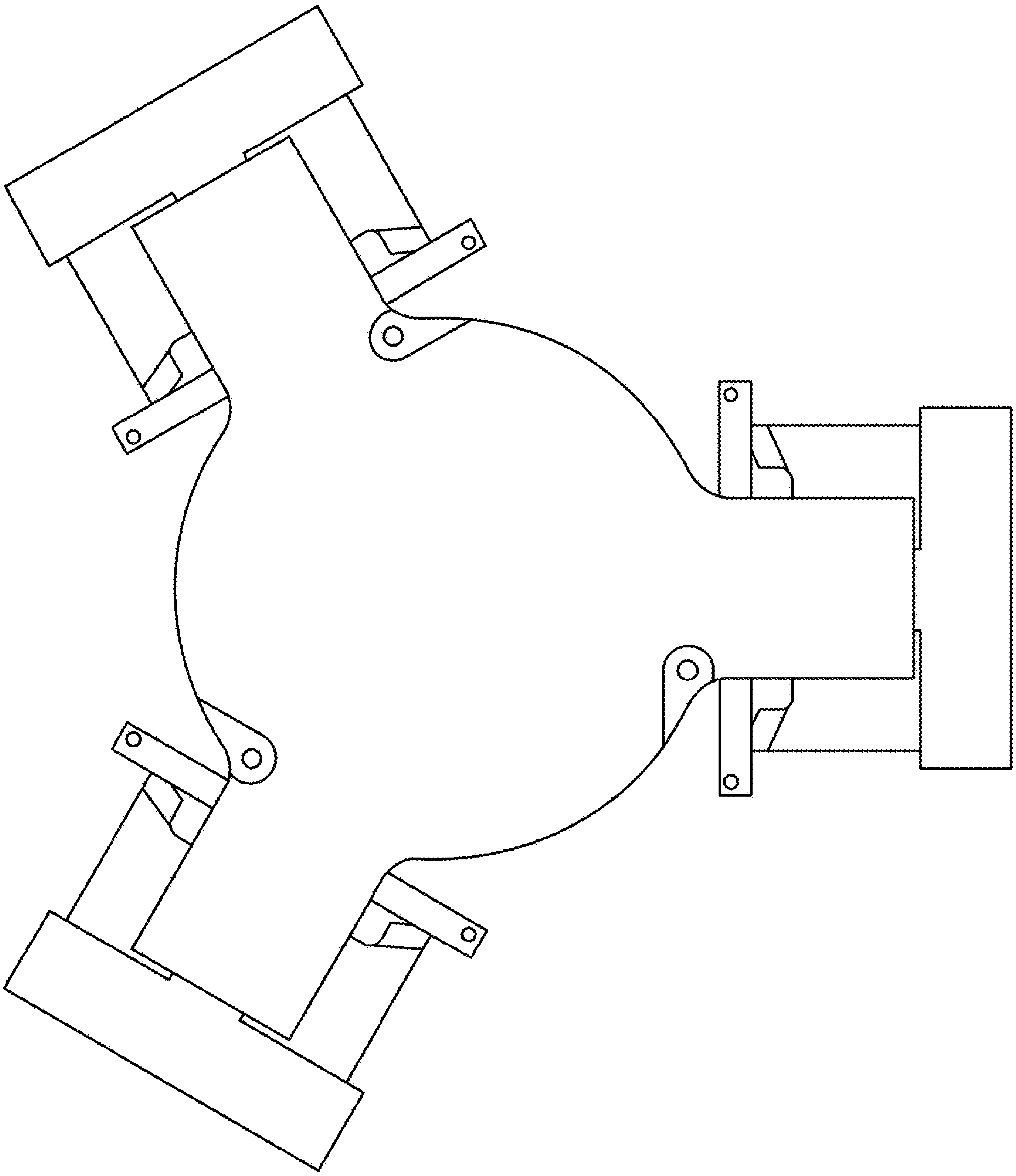

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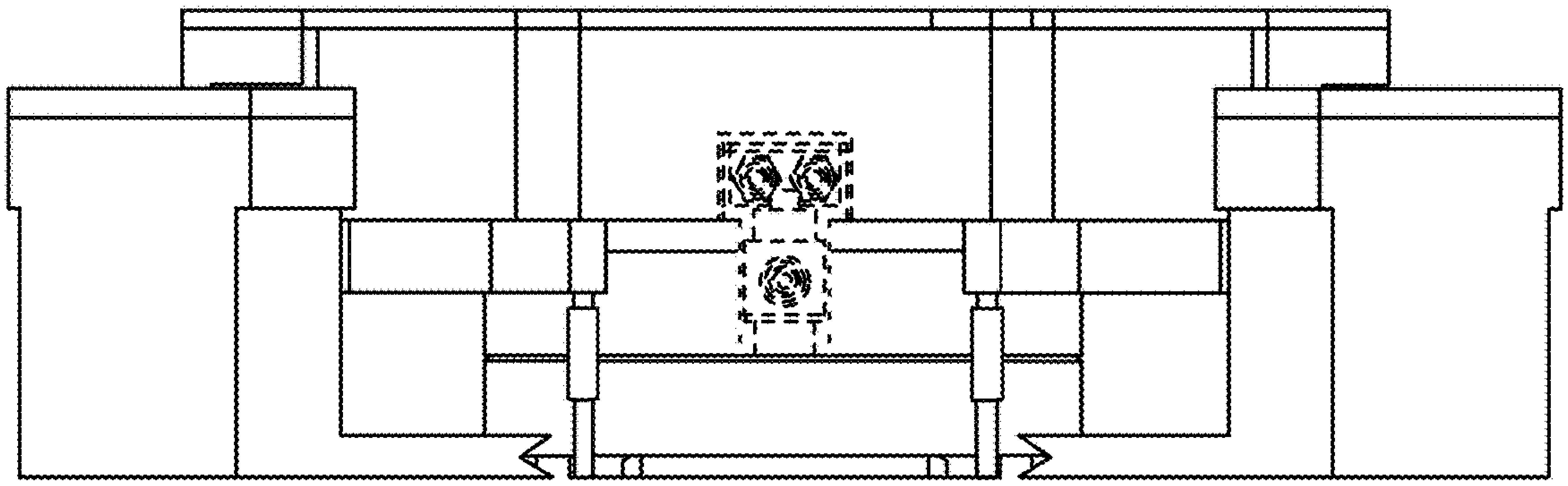

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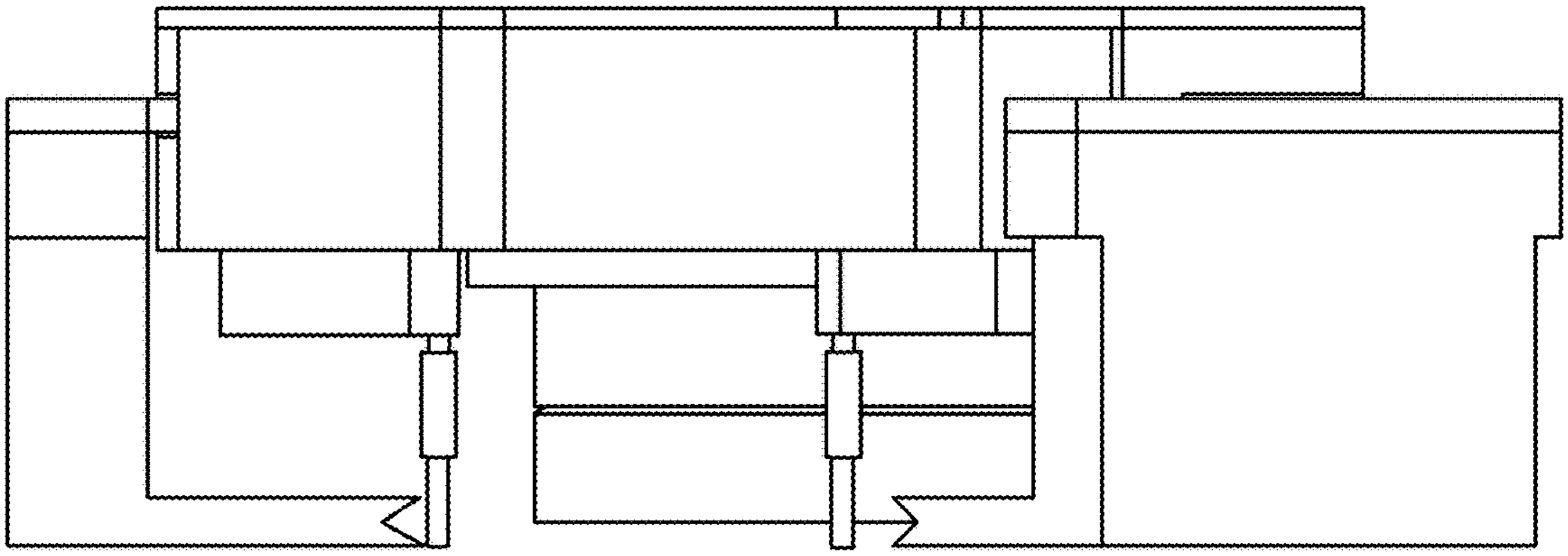


FIG. 24

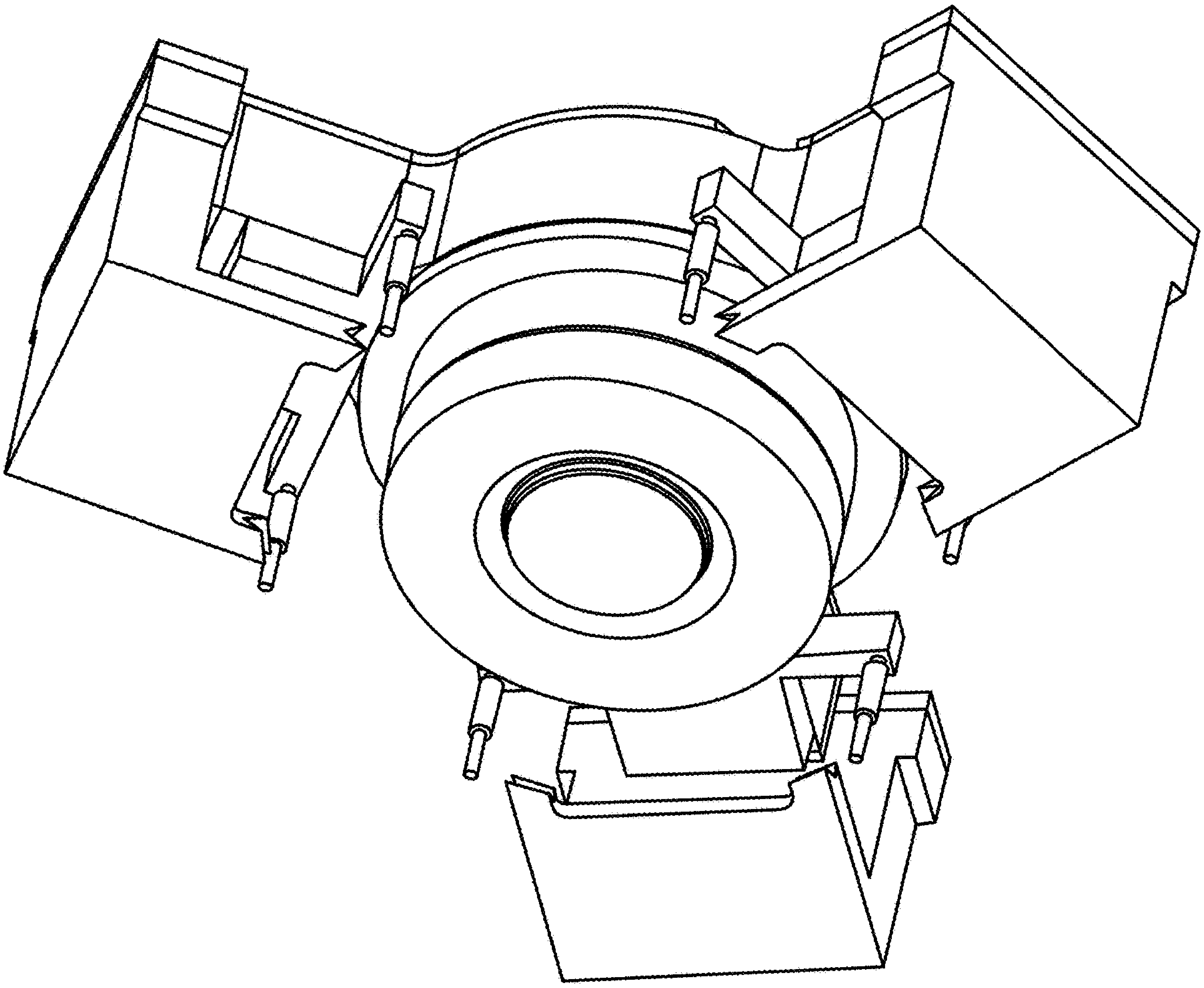


FIG. 25

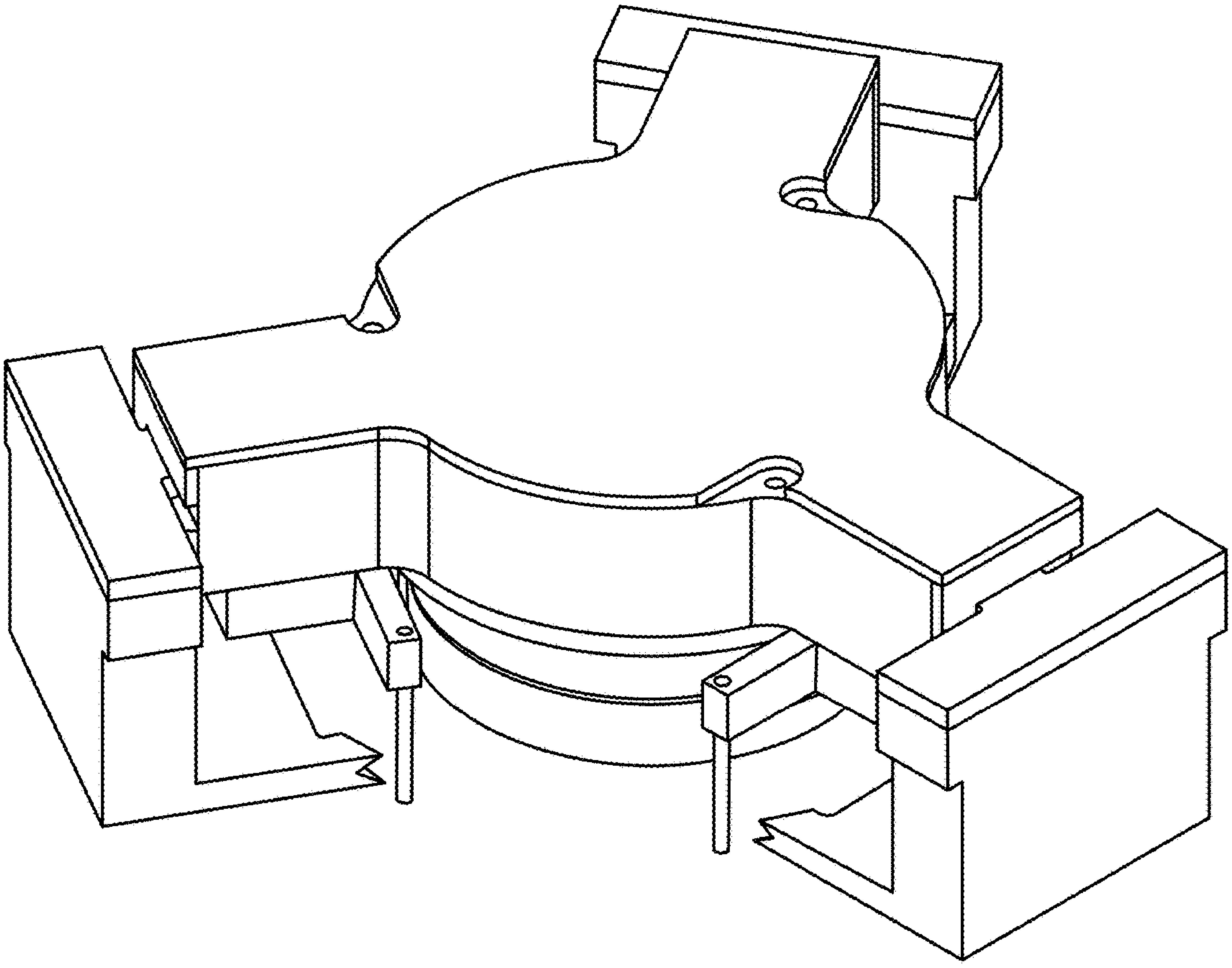


FIG. 26

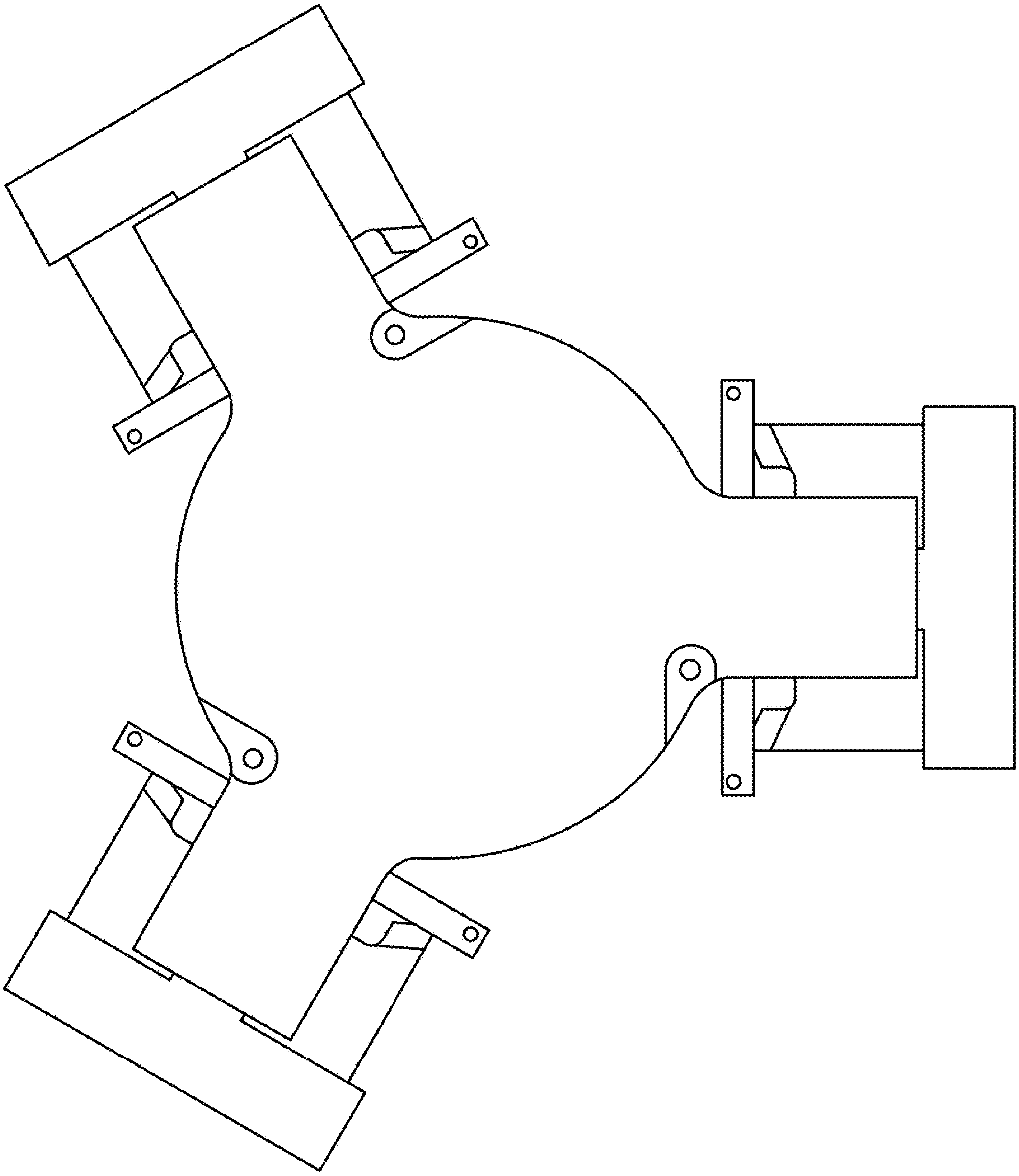
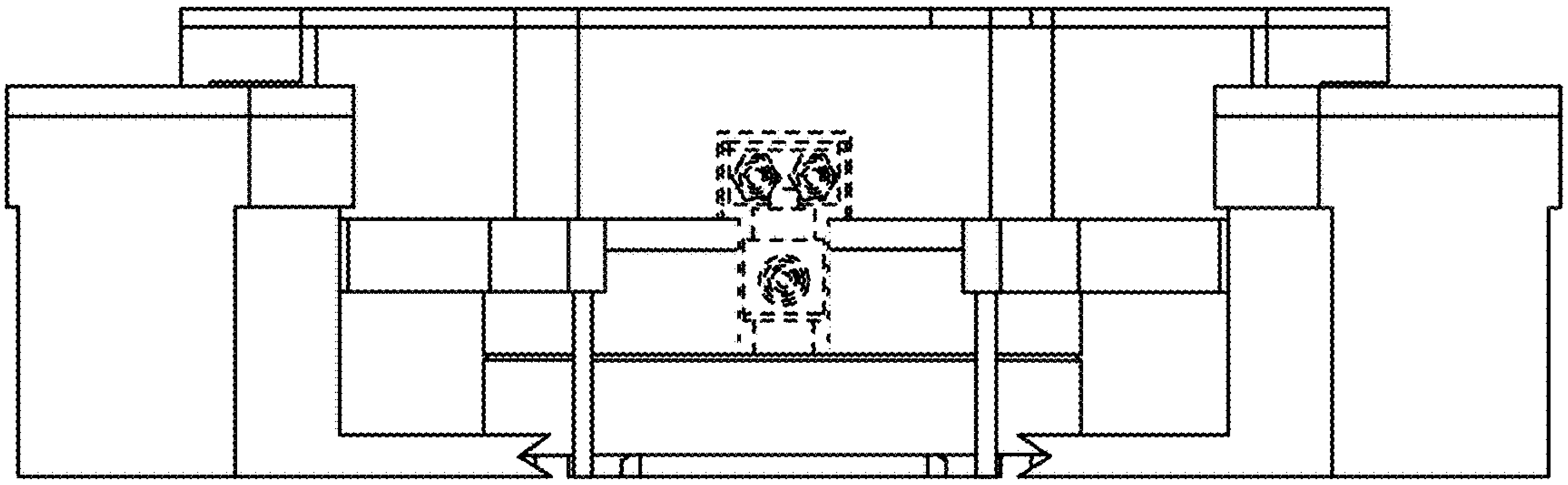


FIG. 27



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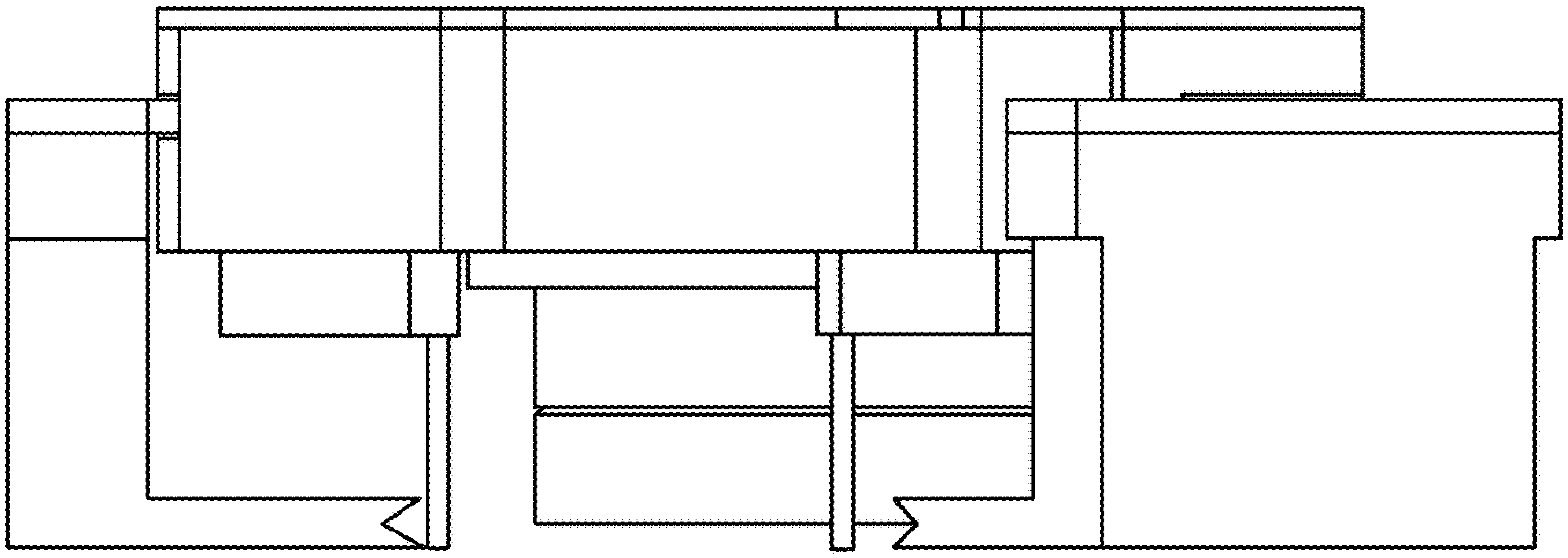

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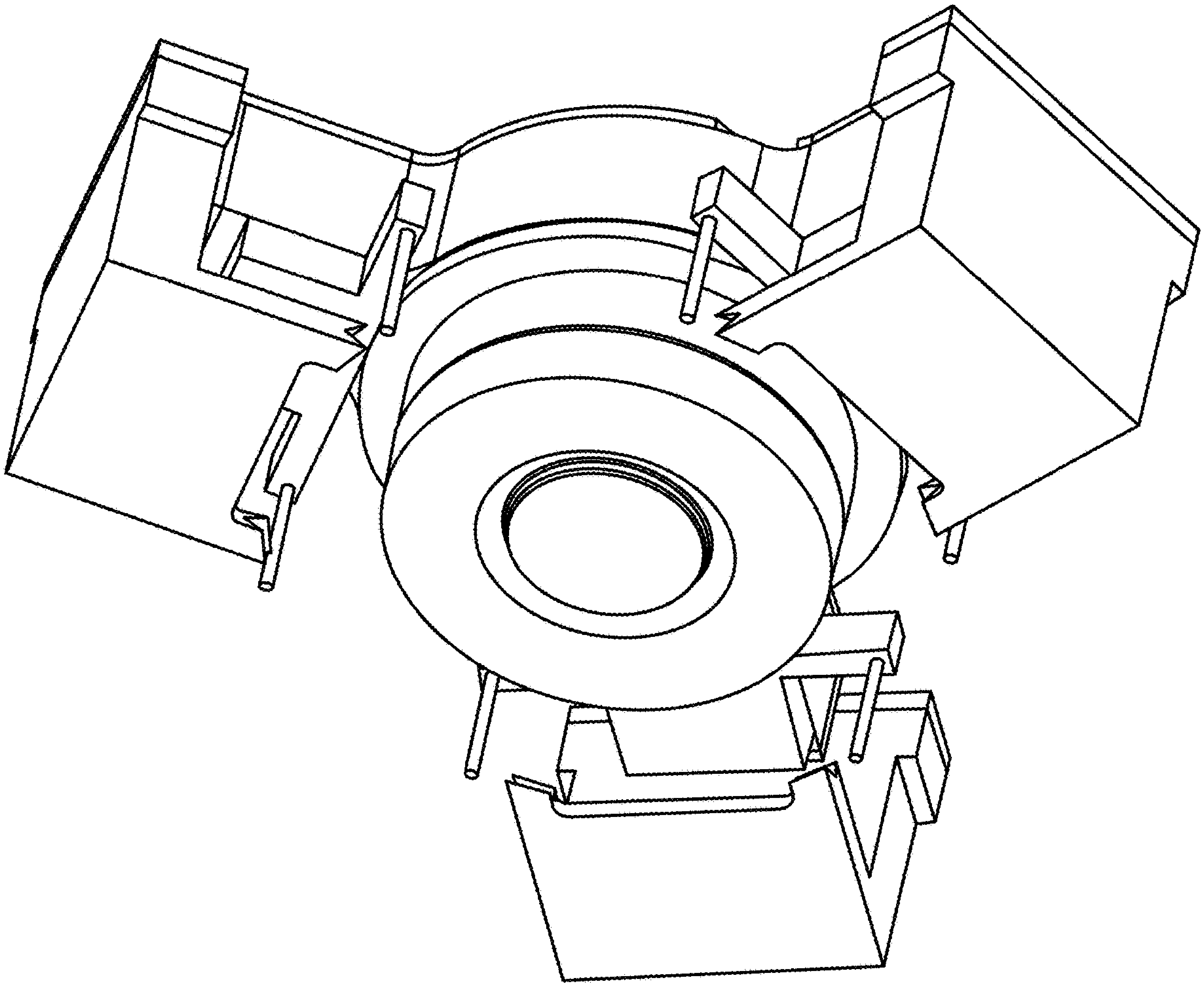

FIG. 30